

REV.	ECH.NO.	APPD.
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特性 : Specifications :

电 器 : Electrical :

结 束 阻 抗 : Contact Resistance

50 milliohms MAX

耐 电 压 : Dielectric Withstanding Voltage :

100 V AC AT Sea Level

结 缘 阻 抗 : Insulation Resistance :

100 MEGA ohms MIN

材 料 : Material : ;

塑 胶 : Housing : PBT

端 子 : Contact : Copper Alloy 铜合金

铁 壳 : Shell : Spcc 铁料

电 镀 : Finish :

端 子 : Contact : Plated Gold in Mating Area

Tin On Solder Tails

接 触 点 镀 金 脚 镀 锡

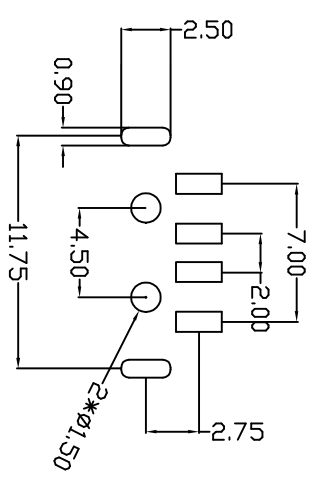
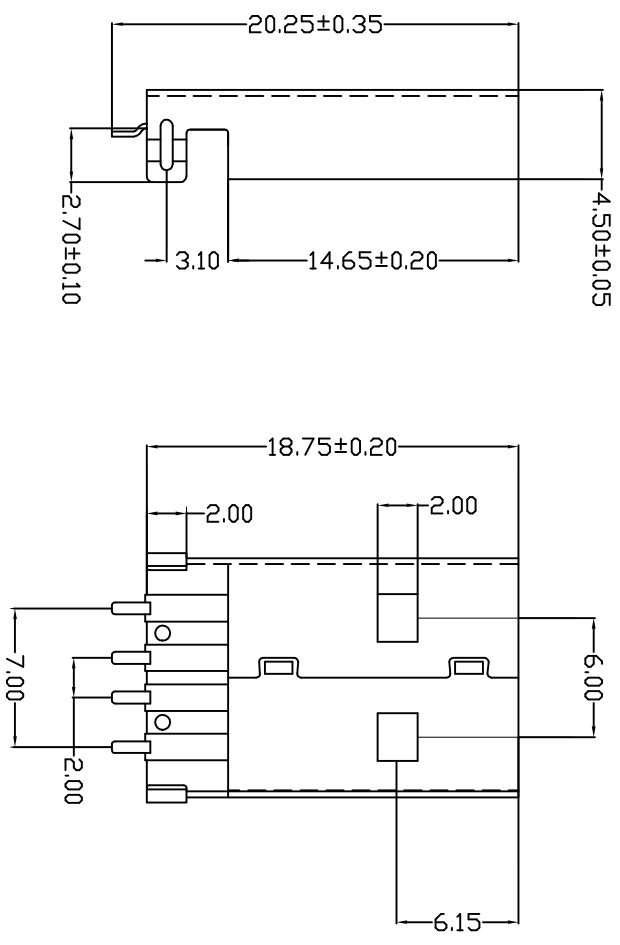
铁 壳 : Sell :

Nickel / Plating 镀镍

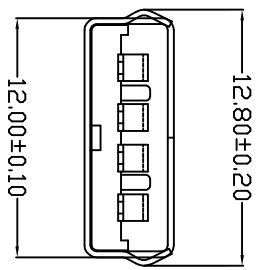
NOTES:

1. terrial:SPCC, T=0.30±0.02mm

2. Plated:50~80u"NKEL UNDER PLATNG ALL OVER I



PCB.LAYoUT



- U218-061X-XXXQX7
- 1: 镀亮镍板
 - 5: 铜壳镀镍
 - 6: 铜壳镀锡
 - 1: 半金1u"
 - J: 半金3u"
 - K: 半金10u"
 - 8: 半金150u"
 - G: 半金/7u"
 - 1: 吸塑盒
 - 8: 胶带
 - 9: 胶带+电胶拉
 - 1: 黑色
 - 2: 白色
 - 5: PBT
 - 6: LCP

TOLERANCE UNLESS OTHERWISE SPECIFIED	XXX ±0.10	XX ±0.20	.X ±0.30	X' ±3	.XX' ±2
HLW 深圳市华联威电子科技有限公司	HUA LIAN WEI TECHNOLOGY ELECTRONICS CO.,LTD.				

APPROVED		PART NAME:	USB AM沉板SMT		
CHECKED		PART No:	U218-061X-X2X017		
DRAWN	wei hong	PROJECTION:	UNIT:	SCALE	SHEET
DATE	2021.7.30		mm	1:1	10F1
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